### **REMARKS**

The application has been carefully reviewed in light of the Office Action dated May 23, 2003. Claims 1 to 3, 5 and 9 to 18 are in the application, of which Claims 9 to 18 have been withdrawn from consideration pursuant to restriction and election requirements. Of the claims under consideration, Claim 1 is the only independent claim. Reconsideration and further examination are respectfully requested.

In response to the objection to Figure 1 and Figure 2 set out in paragraph 6 of the Office Action, a substitute drawing sheet with a new Figure 1 is submitted herewith.

New Figure 1 is believed to be fully consistent with Figure 2 and withdrawal of the objection is requested.

In the Office Action, Claim 3 was rejected under 35 U.S.C. § 112, second paragraph, in response to which Claim 3 has been amended to improve consistency with Claim 1.

Claims 1 to 4, 7 and 8 were rejected under 35 U.S.C. § 102(e) over U.S.

Patent 6,255,725 (Akagawa). Claims 1 to 4, 7 and 8 were also rejected under 35 U.S.C. §

102(b) over Japan Patent 10-337982 (Watanabe). Claim 6 was rejected under 35 U.S.C. §

103(a) over Akagawa in view of U.S. Patent 5,272,596 (Honore). Withdrawal of the rejections is respectfully requested.

According to Claim 1, the present invention relates to a semiconductor device for transmitting information by using an induction field as a transmission medium. The semiconductor device consists of an IC chip for storing and processing information to be transmitted; a coil for generating the induction field; connecting terminals provided at an end of the coil; wires connecting the IC chip and the connecting terminals; sheets of

tape bonding and fixing a part of one side of the coil; and a resin. In the semiconductor device, the resin integrates the IC chip, the IC chip supporting section, the coil, the wires the connecting terminals, and the sheets of tape with one another. Furthermore, the IC chip supporting section, the coil, and the connecting terminals are formed of the same metal that is patterned.

The present invention contains a number of advantageous features. One such feature is that the coil, connecting terminals and the IC chip supporting section are formed of the same metal that is patterned. This feature may allow for reduced material costs and reduced production cost.

Akagawa is seen to disclose a semiconductor device containing a semiconductor element, in which the semiconductor element, a coil, connecting terminals and wires are sealed between two resin films. The wires connect the connecting terminals to the semiconductor element. Akagawa is not seen to disclose the use of an IC chip supporting section nor is Akagawa seen to teach the material from which such a structure might be produced. However, with reference to Akagawa's figures, the semiconductor element is positioned away from the coil and the connecting terminals. Thus, even if one took the position that a supporting section is inherent, there is no reason to conclude that the supporting section is of the same metal as the coil and the connection terminals. Consequently, Akagawa is not seen to anticipate the present invention.

Watanabe is seen to disclose a semiconductor device containing a semiconductor element, which includes a substrate, an IC chip, a die pad, and antenna coil, connecting terminals, wires and epoxy fillers. The reference is not seen to disclose the

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Commissioner for l Washington, D.C.		Date 7, 3, 2002  Mb. Doy Yc.  Acty, Docket CS500.00633,  Application po. id/052, 450
Response to Official Action Check for \$  Petition under 37 CFR 1.1  Notice of Appeal and Check for priority and cert Issue fee transmittal and Check for priority and cert Other (specify)	(claims fee) 136 and Check for \$	JUL 0 3 MOZ WAR TRADEMINES  Description of the second of t

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FITZPATRICK CELLA HARPER & SCINTO

PATENT APPLICATION

#### 03500.016133.

#### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re A	application of:	)	Group Art Unit: 2811
TADA	YOSHI MUTA	)	Group Art Offit. 2011
Applic	eation No.: 10/052,450	)	
Filed:	January 23, 2002	)	
For:	SEMICONDUCTOR DEVICE, PRODUCTION METHOD THEREFOR, AND ELECTROPHOTOGRAPHIC APPARATUS	) : ) :	July 2, 2002
Comm	viccioner for Patents		

Commissioner for Patents Washington, D.C. 20231

## INFORMATION DISCLOSURE STATEMENT

Sir:

In compliance with the duty of disclosure under 37 C.F.R. § 1.56 and in accordance with the practice under 37 C.F.R. §§ 1.97 and 1.98, the Examiner's attention is directed to the documents listed below and on the enclosed Form PTO-1449. Copies of the listed documents are also enclosed.

- (1) US 2002/0026703 A1
- (2) Japan 10-337982
- (3) Japan 11-144018
- (4) Japan 11-250214

References (2) to (4) are discussed at page 2 of the specification and may be deemed pertinent for the reasons given there. Reference (1) is believed to be an English-language counterpart of reference (4). English-language abstracts for references (2) to (4) are also enclosed.

Inasmuch as the subject application has not yet received a first Office Action, it is believed that this Information Disclosure Statement is timely. See 37 C.F.R. . 1.97(b)(3). Accordingly, the Examiner is urged to study this information in its entirety and to form an independent determination of the materiality of the information to the claimed invention. Additionally, the Examiner is requested to indicate that this information has been considered by initialing the appropriate portion of Form PTO-1449.

Applicant's undersigned attorney may be reached in our Costa Mesa, California office by telephone at (714) 540-8700. All correspondence should continue to be directed to our address given below.

Respectfully submitted,

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feature of sheets of tape bonding and fixing a part of one side of the coil. Therefore, it does not anticipate the present invention.

In view of the foregoing, Claim 1 and the claims which depend therefrom are seen to be in allowable condition. Once the claims under consideration have been allowed, rejoinder of Claim 5 and 18, belonging to the elected group, is respectfully requested.

# REQUEST FOR CONSIDERATION OF INFORMATION DISCLOSURE STATEMENT

The Office Action indicates that the Information Disclosure Statement (IDS) filed on July 3, 2002 has not been considered, for alleged failure to provide a list of cited documents. Applicants respectfully submit that the Information Disclosure Statement was fully compliant with 37 CFR 1.98(a)(1) upon filing with the Patent Office, as evidenced by a return receipt postcard bearing the stamp of the Patent and Trademark Office, a copy of which is attached hereto. The stamped postcard shows that the Patent Office received the Information Disclosure Statement, a Form PTO-1449 and 4 documents on July 3, 2003. Furthermore, the Examiner was provided with two lists, one within the attached Form PTO-1449 and one within the Information Disclosure Statement itself, both listing all the patents and publications submitted.

For the Examiner's convenience a full copy of the Information Disclosure Statement, together with its Form PTO-1449, is also attached. Applicants respectfully request the Examiner to return an initialed copy of the Form PTO-1449, indicating the references cited thereon were considered.

Applicant's undersigned attorney may be reached in our Costa Mesa,

California office by telephone at (714) 540-8700. All correspondence should continue to be directed to our address given below.

Respectfully submitted,

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FORM PTO 1449	(modified)		ATTY DOCKET NO. 03500.016133. APPLICATION NO. 10/052,450								
p	J.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	2)	APPLICANT TADAYOSHI MUTA								
LIST OF REFERENCES CITED BY APPLICANT(S) (Use several sheets if necessary)			FILING DATE January 23, 2002		GROUP 2811						
U.S. PATENT DOCUMENTS											
*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE					
ev	2002/0026703 A1	3/7/02	Oku et al.	29	602.1						
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		FOR	EIGN PATENT DOCUMENTS								
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES/NO/ OR ABSTRACT					
KL	10-337982	12/22/98	3 Japan			Abstract					
EC	11-144018	5/28/99	Japan			Abstract					
EL	11-250214	9/17/99	Japan			Abstract					
,	OTHER DO	DCUMENT(S) (	Including Author, Title, Date, Pertinent Pages, Etc.)								
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Sheet\_\_1\_ of \_\_1\_